



Description

The 74ALS08 quad 2-input AND gate is fabricated using a 2μm 40V Bipolar process. The device consists of four independent 2-input AND gates with standard push-pull outputs and performs the Boolean function $Y = A \bullet B$ or $Y = A + B$. All inputs are protected against ESD and excess voltage transients.

Features:

- High speed – 4ns (Min) propagation delay
- Direct drop-in replacement for obsolete components in long term programs.

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Ordering Information

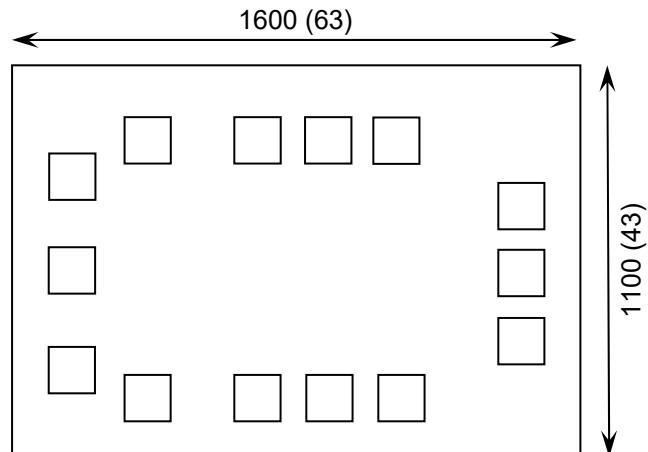
The following part suffixes apply:

- No suffix - MIL-STD-883 /2010B Visual Inspection

For High Reliability versions of this product please see

[54ALS08](#)

Die Dimensions in μm (mils)



Supply Formats:

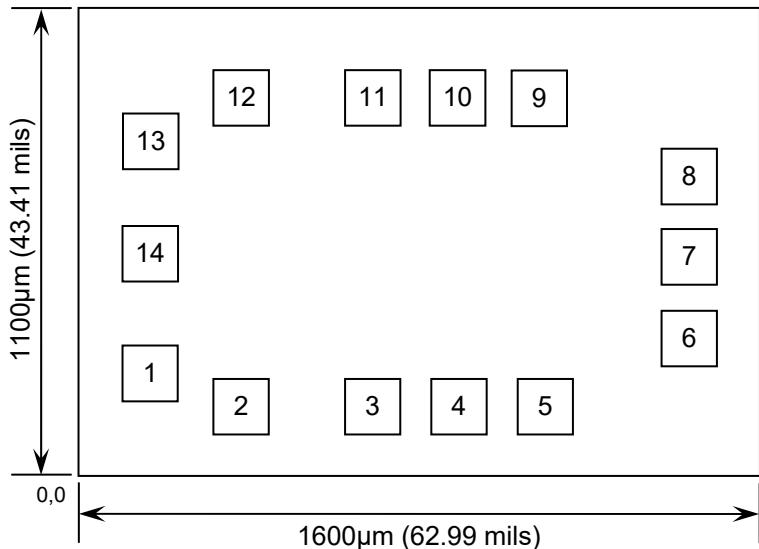
- Default – Die in Waffle Pack (300 per tray capacity)
- Sawn Wafer on Tape – On request
- Unsawn Wafer – On request
- Die Thickness <> 350μm(14 Mils) – On request
- Assembled into Ceramic Package – On request

Mechanical Specification

Die Size (Unsawn)	1600 x 1100 63 x 43	μm mils
Minimum Bond Pad Size	130 x 130 5.12 x 5.12	μm mils
Die Thickness	350 (± 20) 13.78 (± 0.79)	μm mils
Top Metal Composition	Al 1%Si 1.1μm	
Back Metal Composition	N/A – Bare Si	



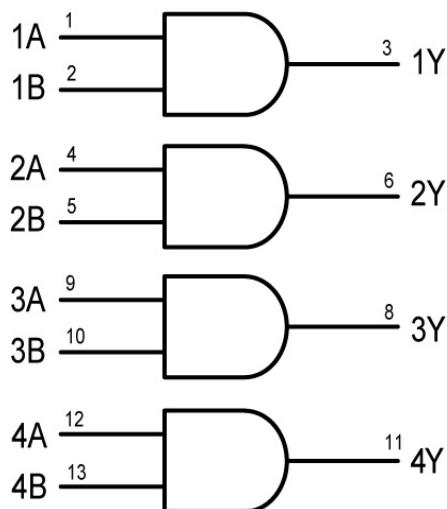
Pad Layout and Functions



PAD	FUNCTION	COORDINATES (mm)	
		X	Y
1	1A	0.100	0.180
2	1B	0.315	0.100
3	1Y	0.625	0.100
4	2A	0.825	0.100
5	2B	1.025	0.100
6	2Y	1.370	0.260
7	GND	1.370	0.450
8	3Y	1.370	0.640
9	3A	1.015	0.825
10	3B	0.825	0.825
11	4Y	0.625	0.825
12	4A	0.425	0.825
13	4B	0.100	0.725
14	V _{cc}	0.100	0.460

CONNECT CHIP BACK TO GND OR FLOAT

Logic Diagram



Function Table

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

H = High level (steady state)
L = Low level (steady state)

Pad 14 = V_{cc}
Pad 7 = GND



Absolute Maximum Ratings¹

PARAMETER	SYMBOL	VALUE	UNIT
DC Supply Voltage	V _{CC}	7.0	V
DC Input Voltage	V _{IN}	7.0	V
Storage Temperature Range	T _{STG}	-65 to 150	°C

1. Operation above the absolute maximum rating may cause device failure. Operation at the absolute maximum ratings, for extended periods, may reduce device reliability.

Recommended Operating Conditions

PARAMETER	SYMBOL	MIN	MAX	UNITS
Supply Voltage	V _{CC}	4.5	5.5	V
High-Level Input Voltage	V _{IH}	2	-	V
Low-Level Input Voltage	V _{IL}	-	0.8	V
High-Level Output Current	I _{OH}	-	-0.4	mA
Low-Level Output Current	I _{OL}	-	8	mA
Operating Temperature Range	T _J	-40	+55	°C

DC Electrical Characteristics² T_J = -40°C to 85°C unless otherwise specified

PARAMETER	SYMBOL	CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
Minimum High-Level Input Voltage	V _{IH}	-	2	-	-	V
Maximum Low-Level Input Voltage	V _{IL}	-	-	-	0.8	V
Input Clamp Diode Voltage	V _{IK}	V _{CC} = MIN I _{IN} = -18mA	-	-	-1.5	V
Output Voltage High	V _{OH}	V _{CC} = 4.5V to 5.5V, I _{OH} = -0.4mA	V _{CC} - 2	-	-	V
Output Voltage Low	V _{OL}	V _{CC} = 4.5V	I _{OL} = 4mA	0.25	0.4	V
			I _{OL} = 8mA	0.35	0.5	
Input Current	I _{IN}	V _{CC} = 5.5V, V _{IN} = 7V	-	-	0.1	mA
Input High Current	I _{IH}	V _{CC} = 5.5V, V _{IN} = 2.7V	-	-	20	µA
Input Low Current	I _{IL}	V _{CC} = 5.5, V _{IN} = 0.4V	-	-	-0.1	mA
Output Current ³	I _O	V _{CC} = 5.5, V _{OUT} = 2.25V	-30	-	-112	mA
Power Supply Current (Total)	I _{CCH}	V _{CC} = 5.5V, V _{IN} = 4.5V	-	1.3	2.4	mA
	I _{CCL}	V _{CC} = 5.5V, V _{IN} = 0V	-	2.2	4	

2. All typical values @ V_{CC} = 5V, T_J = 25°C.

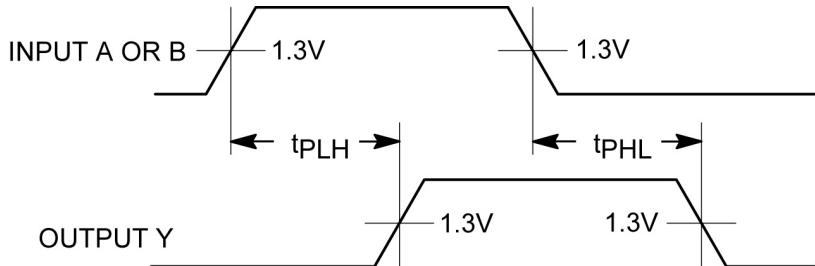
3. Output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{os}

AC Electrical Characteristics⁴ $T_J = -40^\circ\text{C}$ to 85°C unless otherwise specified

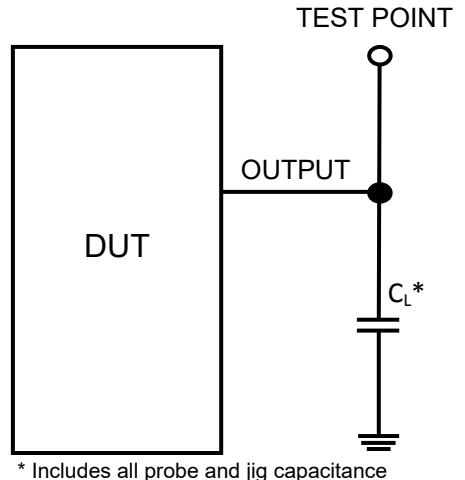
PARAMETER	SYMBOL	CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
Propagation Delay, A or B to output Y	t_{PLH}	$V_{CC} = 4.5$ to 5.5V , $C_L = 50\text{pF}$, $R_L = 500\Omega$	4	-	14	ns
	t_{PHL}		3	-	10	

4. Not production tested in die form, characterized by chip design and tested in package.

Switching Waveform



Test Circuit



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